

INN650D150A

1. General description

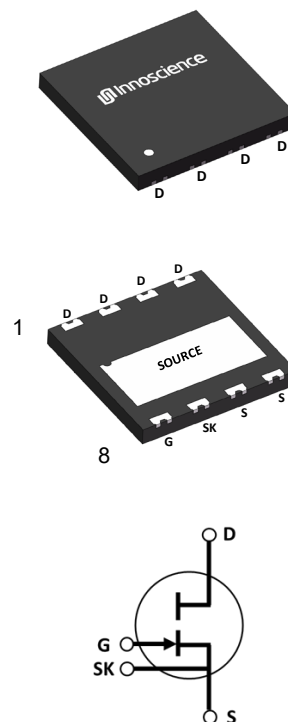
650V GaN-on-silicon Enhancement-mode Power Transistor in Dual Flat No-lead package (DFN) with 8 mm × 8 mm size

2. Features

- Enhancement mode transistor-Normally off power switch
- Ultra high switching frequency
- No reverse-recovery charge
- Low gate charge, low output charge
- Qualified for industrial applications according to JEDEC Standards
- ESD safeguard
- RoHS, Pb-free, REACH-compliant

3. Applications

- AC-DC converters
- DC-DC converters
- Totem pole PFC
- Fast battery charging
- High density power conversion
- High efficiency power conversion



4. Key performance parameters

Table 1 Key performance parameters at $T_j = 25\text{ }^{\circ}\text{C}$

Parameter	Value	Unit
$V_{DS,max}$	650	V
$R_{DS(on),max}$ @ $V_{GS} = 6\text{ V}$	150	m Ω
$Q_{G,typ}$ @ $V_{DS} = 400\text{ V}$	3	nC
$I_{D,pulse}$	32	A
Q_{OSS} @ $V_{DS} = 400\text{ V}$	28	nC
Q_{rr} @ $V_{DS} = 400\text{ V}$	0	nC

5. Pin information

Table 2 Pin information

Gate	Drain	Kelvin Source	Source
8	1,2,3,4	7	5,6

Table 3 Ordering information

Type/Ordering Code	Package	Marking (Product Code)
INN650D150A	DFN 8X8	INN65D150A

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6. Maximum ratings

at $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Continuous application of maximum ratings can deteriorate transistor lifetime. For further information, contact Innoscence sales office.

Table 4 Maximum ratings

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Drain source voltage	$V_{DS,max}$	-	-	650	V	$V_{GS} = 0\text{ V}$, $I_D = 25\text{ }\mu\text{A}$
Drain source voltage transient ¹	$V_{DS(transient)}$	-	-	750	V	$V_{GS} = 0\text{ V}$, $V_{DS} = 750\text{ V}$
Continuous current, drain source	I_D	-	-	17	A	$T_c = 25\text{ }^{\circ}\text{C}$
Pulsed current, drain source ²	$I_{D,pulse}$	-	-	32	A	$T_c = 25\text{ }^{\circ}\text{C}$; $V_G = 6\text{ V}$; See Figure 16;
Pulsed current, drain source ²	$I_{D,pulse}$	-	-	23	A	$T_c = 125\text{ }^{\circ}\text{C}$; $V_G = 6\text{ V}$; See Figure 17;
Gate source voltage, continuous ³	V_{GS}	-1.4	-	+7	V	$T_j = -55\text{ }^{\circ}\text{C}$ to $150\text{ }^{\circ}\text{C}$
Gate source voltage, pulsed	$V_{GS,pulse}$	-20	-	+10	V	$T_j = -55\text{ }^{\circ}\text{C}$ to $150\text{ }^{\circ}\text{C}$; $t_{PULSE} = 50\text{ ns}$, $f = 100\text{ kHz}$ open drain
Power dissipation	P_{tot}	-	-	113	W	$T_c = 25\text{ }^{\circ}\text{C}$
Operating temperature	T_j	-55	-	+150	$^{\circ}\text{C}$	
Storage temperature	T_{stg}	-55	-	+150	$^{\circ}\text{C}$	

1 $V_{DS(transient)}$ is intended for surge rating during non-repetitive events, $t_{PULSE} < 1\text{ }\mu\text{s}$

2 Pulse = 300 μs

3 The minimum V_{GS} is clamped by ESD protection circuit, as shown in Figure 10

7. Thermal characteristics

Table 5 Thermal characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction-case	R_{thJC}	-	-	1.1	°C/W	
Reflow soldering temperature	T_{sold}	-	-	260	°C	MSL3

8. Electric characteristics

at $T_j = 25\text{ }^{\circ}\text{C}$, unless specified otherwise

Table 6 Static characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Gate threshold voltage	$V_{GS(th)}$	1.2	1.6	2.2	V	$I_D = 17.2\text{ mA}$; $V_{DS} = V_{GS}$; $T_j = 25\text{ }^{\circ}\text{C}$
		-	1.5	-		$I_D = 17.2\text{ mA}$; $V_{DS} = V_{GS}$; $T_j = 125\text{ }^{\circ}\text{C}$
Drain-source leakage current	I_{DSS}	-	0.7	25	μA	$V_{DS} = 650\text{ V}$; $V_{GS} = 0\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$
		-	6	200		$V_{DS} = 650\text{ V}$; $V_{GS} = 0\text{ V}$; $T_j = 150\text{ }^{\circ}\text{C}$
Gate-source leakage current	I_{GSS}	-	30	-	μA	$V_{GS} = 6\text{ V}$; $V_{DS} = 0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	115	150	$\text{m}\Omega$	$V_{GS} = 6\text{ V}$; $I_D = 5\text{ A}$; $T_j = 25\text{ }^{\circ}\text{C}$
		-	234	-	$\text{m}\Omega$	$V_{GS} = 6\text{ V}$; $I_D = 5\text{ A}$; $T_j = 150\text{ }^{\circ}\text{C}$
Gate resistance	R_G	-	1.4	-	Ω	$f = 5\text{ MHz}$; open drain

Table 7 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	110	-	pF	$V_{GS} = 0\text{ V}$; $V_{DS} = 400\text{ V}$; $f = 100\text{ kHz}$
Output capacitance	C_{oss}	-	30	-	pF	$V_{GS} = 0\text{ V}$; $V_{DS} = 400\text{ V}$; $f = 100\text{ kHz}$
Reverse transfer capacitance	C_{rss}	-	0.46	-	pF	$V_{GS} = 0\text{ V}$; $V_{DS} = 400\text{ V}$; $f = 100\text{ kHz}$
Effective output capacitance, energy related ¹	$C_{o(er)}$	-	42	-	pF	$V_{GS} = 0\text{ V}$; $V_{DS} = 0\text{ to }400\text{ V}$
Effective output capacitance, time related ²	$C_{o(tr)}$	-	68	-	pF	$V_{GS} = 0\text{ V}$; $V_{DS} = 0\text{ to }400\text{ V}$
Output charge	Q_{oss}	-	28	-	nC	$V_{GS} = 0\text{ V}$; $V_{DS} = 0\text{ to }400\text{ V}$
Turn-on delay time	$t_{d(on)}$	-	3	-	nS	See Figure 22
Turn-off delay time	$t_{d(off)}$	-	7	-	nS	See Figure 22
Rise time	t_r	-	5	-	nS	See Figure 22
Fall time	t_f	-	5	-	nS	See Figure 22

¹ $C_{o(er)}$ is the fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 400 V

² $C_{o(tr)}$ is the fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 400 V

Table 8 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Gate charge	Q_G	-	3	-	nC	$V_{GS} = 0 \text{ to } 6 \text{ V}; V_{DS} = 400 \text{ V}; I_D = 5 \text{ A}$
Gate-source charge	Q_{GS}	-	0.28	-	nC	
Gate-drain charge	Q_{GD}	-	1.63	-	nC	
Gate Plateau Voltage	V_{Plat}	-	2.3	-	V	$V_{DS} = 400 \text{ V}; I_D = 5 \text{ A}$

Table 9 Reverse conduction characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Source-Drain reverse voltage	V_{SD}	-	2.6	-	V	$V_{GS} = 0 \text{ V}; I_S = 5 \text{ A}$
Pulsed current, reverse	$I_{S,pulse}$	-	-	32	A	$V_{GS} = 6 \text{ V}$
Reverse recovery charge	Q_{rr}	-	0	-	nC	$I_{SD} = 5 \text{ A}; V_{DS} = 400 \text{ V}$
Reverse recovery time	t_{rr}	-	0	-	ns	
Peak reverse recovery current	I_{rrm}	-	0	-	A	

9. Electric characteristics diagrams

at $T_j = 25\text{ }^{\circ}\text{C}$, unless specified otherwise

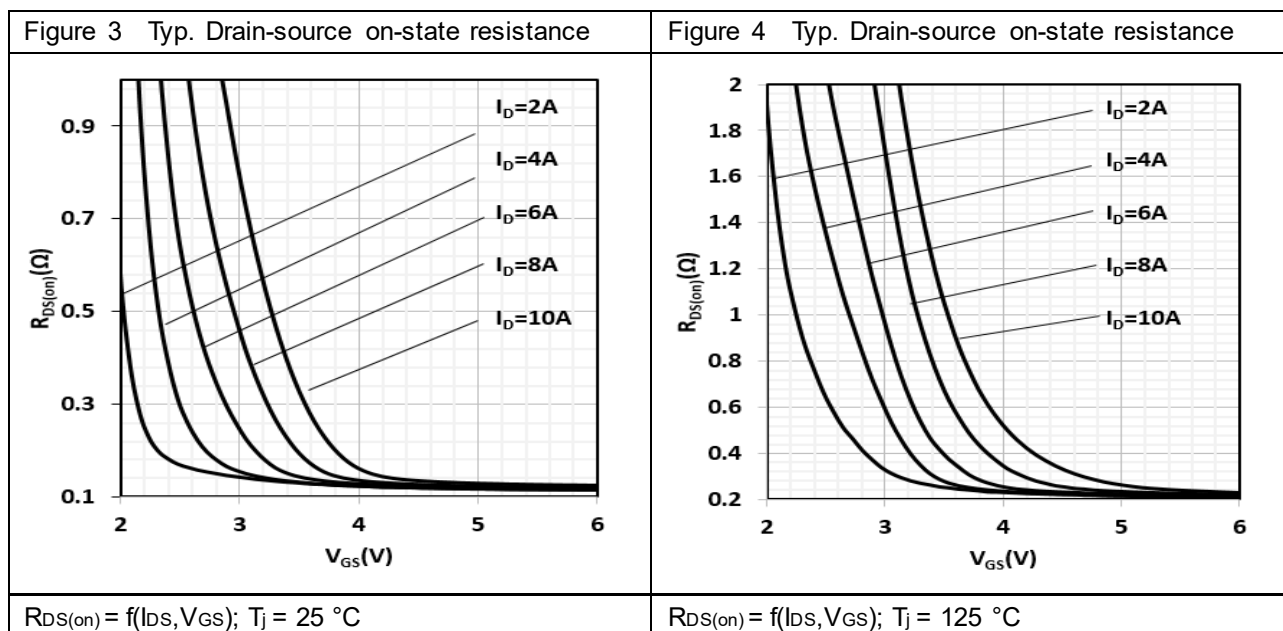
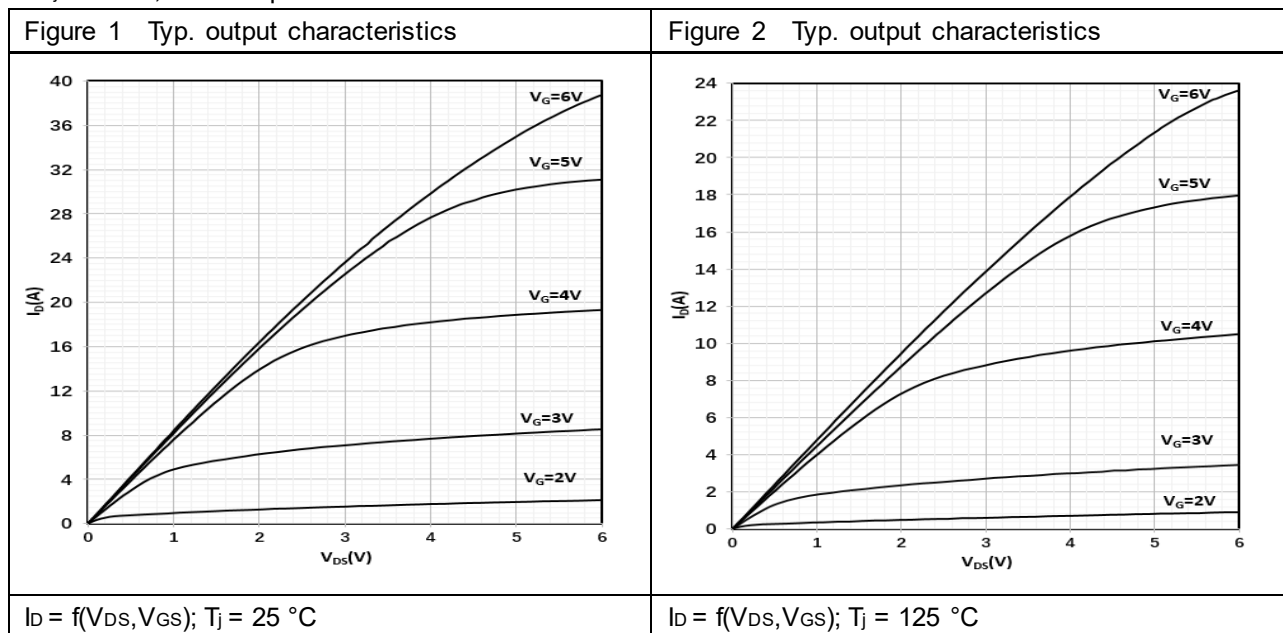
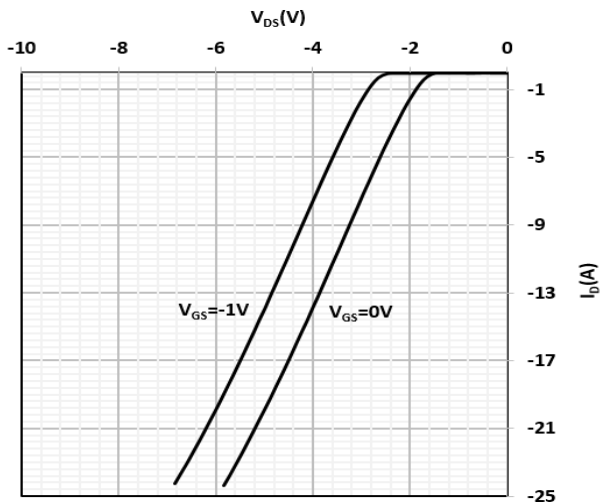
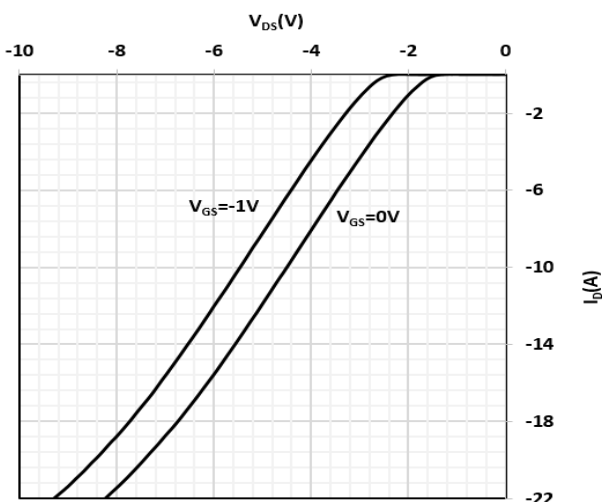


Figure 5 Typ. channel reverse characteristics



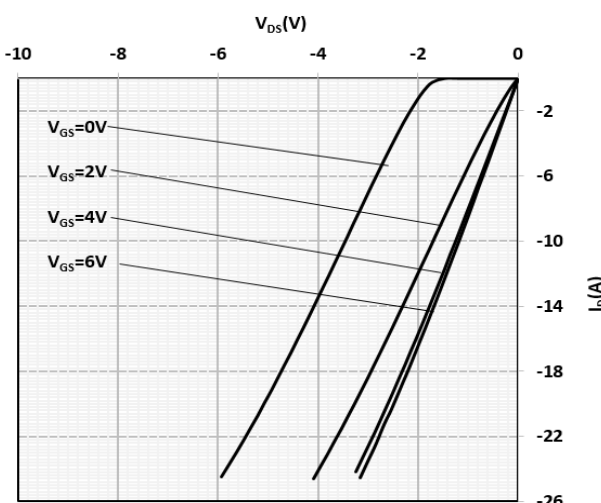
$I_D = f(V_{DS}, V_{GS}); T_j = 25\text{ }^{\circ}\text{C}$

Figure 6 Typ. channel reverse characteristics



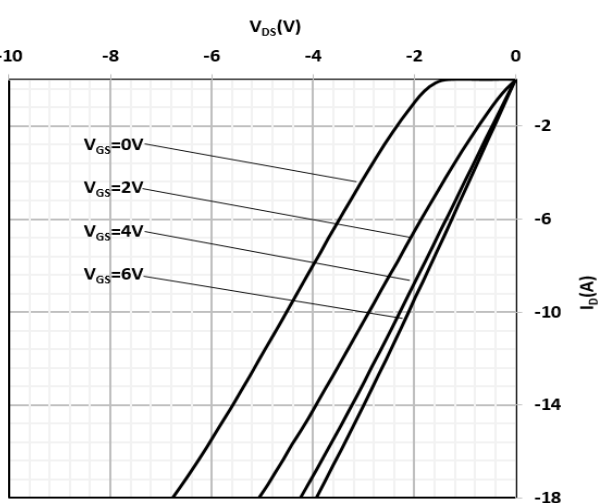
$I_D = f(V_{DS}, V_{GS}); T_j = 125\text{ }^{\circ}\text{C}$

Figure 7 Typ. channel reverse characteristics



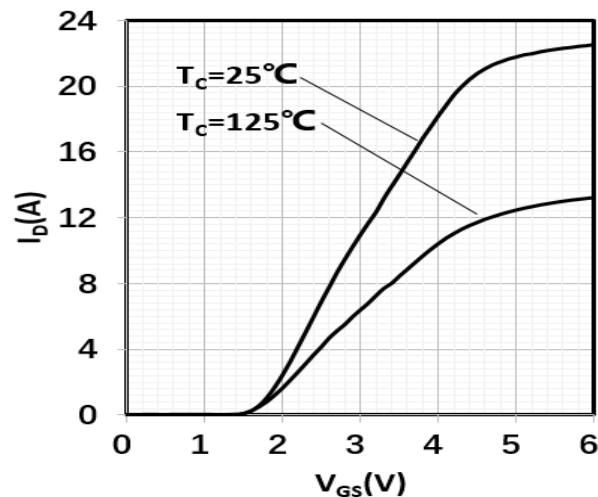
$I_D = f(V_{DS}, V_{GS}); T_j = 25\text{ }^{\circ}\text{C}$

Figure 8 Typ. channel reverse characteristics



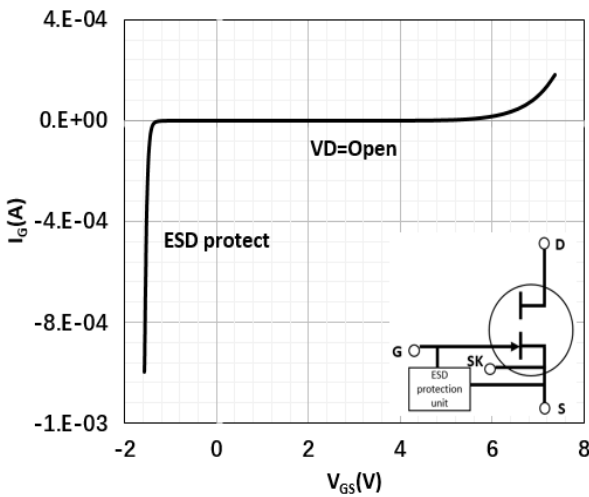
$I_D = f(V_{DS}, V_{GS}); T_j = 125\text{ }^{\circ}\text{C}$

Figure 9 Typ. transfer characteristics



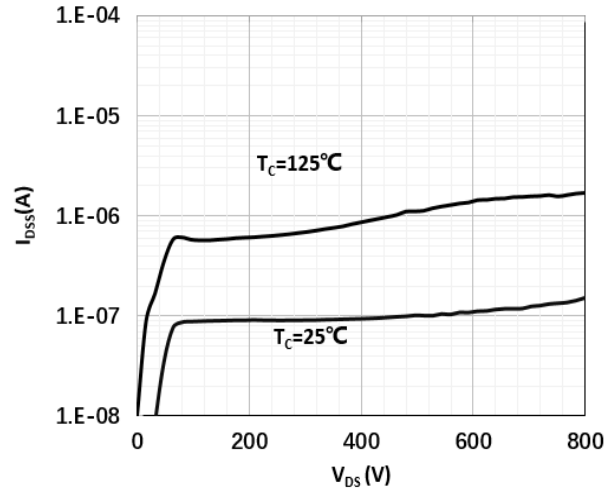
$I_D = f(V_{GS})$; $V_{DS} = 3\text{ V}$

Figure 10 Typ. Gate-to-Source leakage



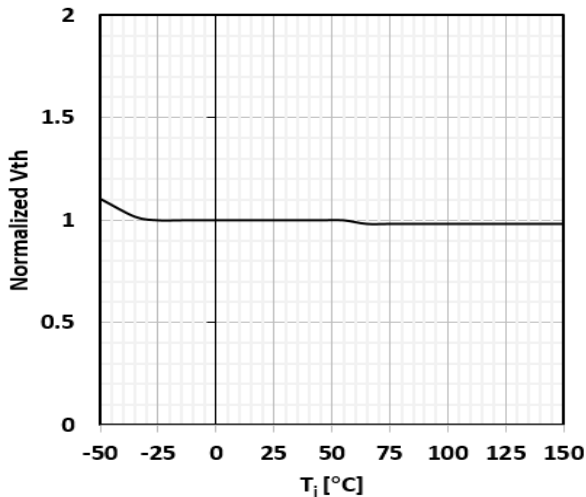
$I_g = f(V_{GS})$; I_g reverse turn on by ESD unit

Figure 11 Drain-source leakage characteristics



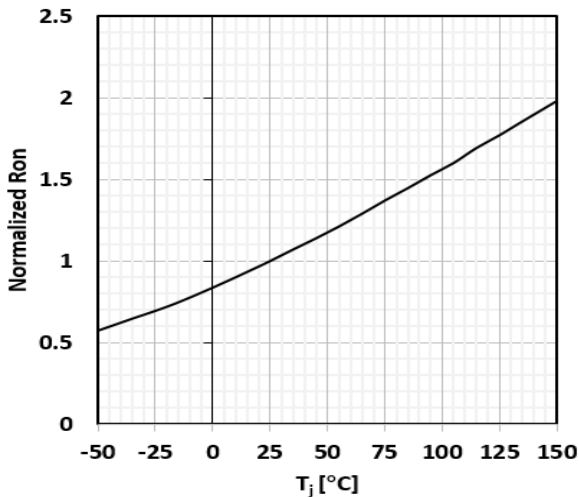
$I_{DSS} = f(V_{DS})$; $V_{GS} = 0\text{ V}$

Figure 12 Gate threshold voltage



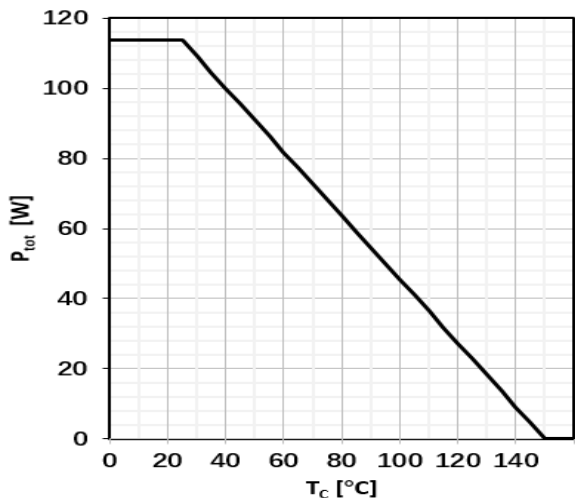
$V_{TH} = f(T_j); V_{GS} = V_{DS}; I_D = 17.2 \text{ mA}$

Figure 13 Drain-source on-state resistance



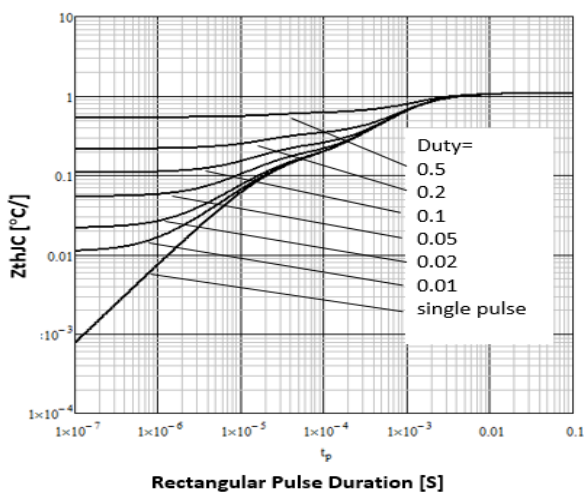
$R_{DS(on)} = f(T_j); I_D = 5 \text{ A}; V_G = 6 \text{ V}$

Figure 14 Power dissipation



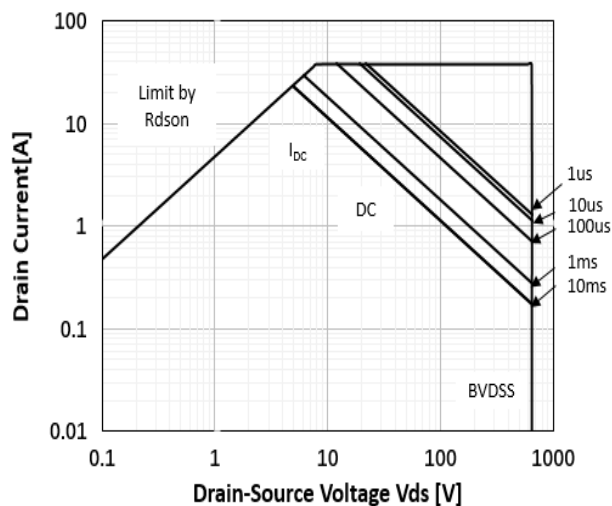
$P_{tot} = f(T_c)$

Figure 15 Max.transient thermal impedance



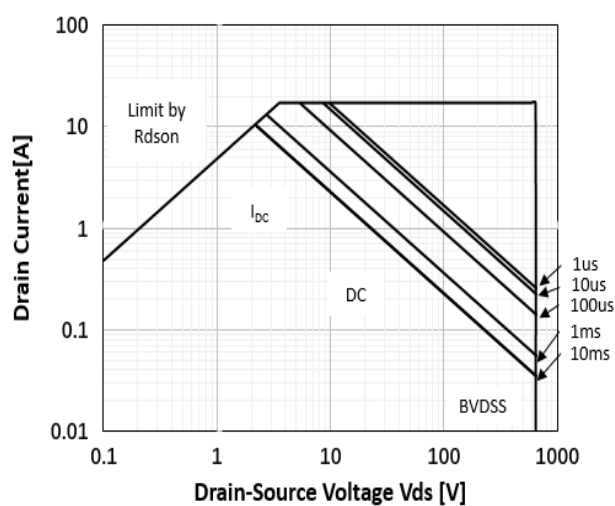
$Z_{thJC} = f(t_P, D)$

Figure 16 Safe operating area



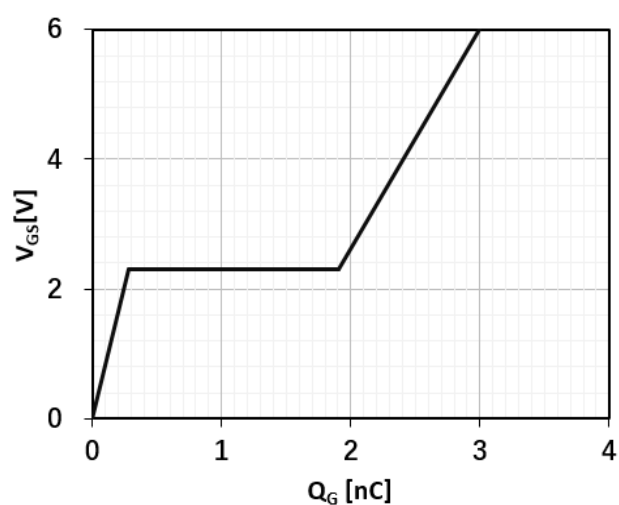
$$I_D = f(V_{DS}); T_C = 25\text{ }^{\circ}\text{C}$$

Figure 17 Safe operating area



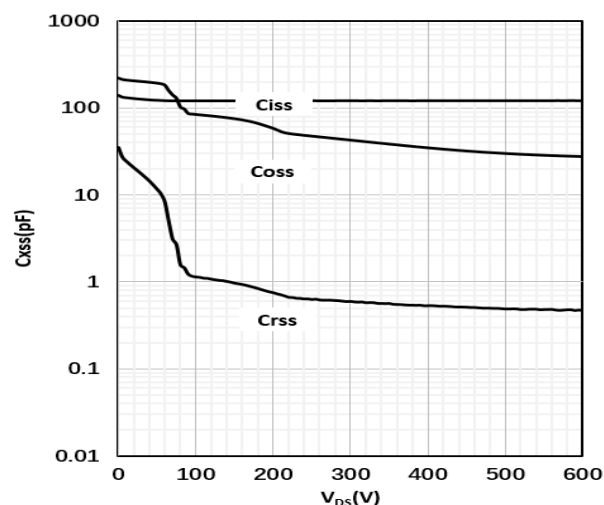
$$I_D = f(V_{DS}); T_C = 125\text{ }^{\circ}\text{C}$$

Figure 18 Typ. gate charge



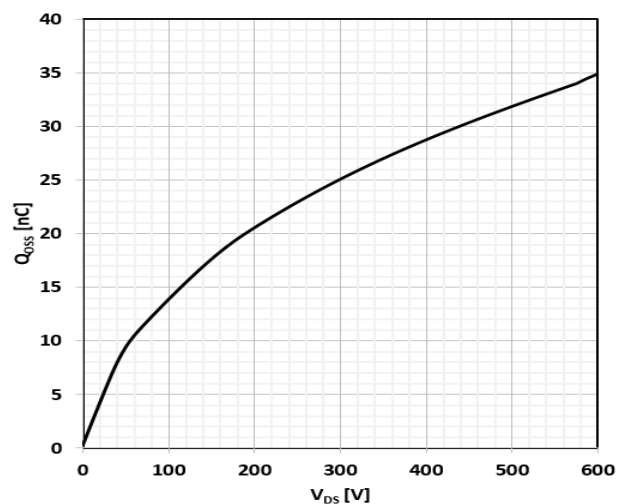
$$V_{GS} = f(Q_G); V_{DCLINK} = 400\text{ V}; I_D = 5\text{ A}$$

Figure 19 Typ. capacitances



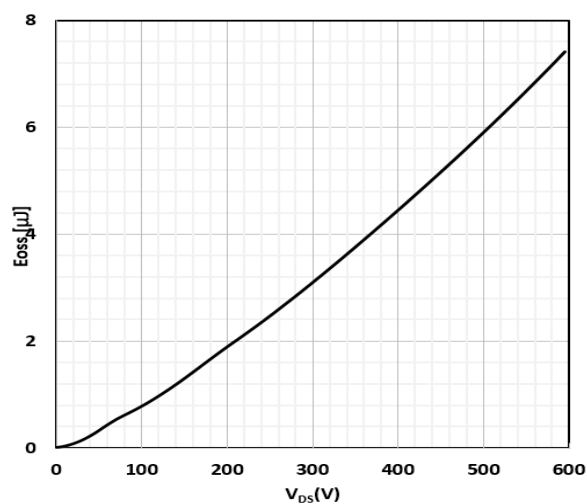
$$C_{XSS} = f(V_{DS}); \text{Freq.} = 100\text{ kHz}$$

Figure 20 Typ. output charge



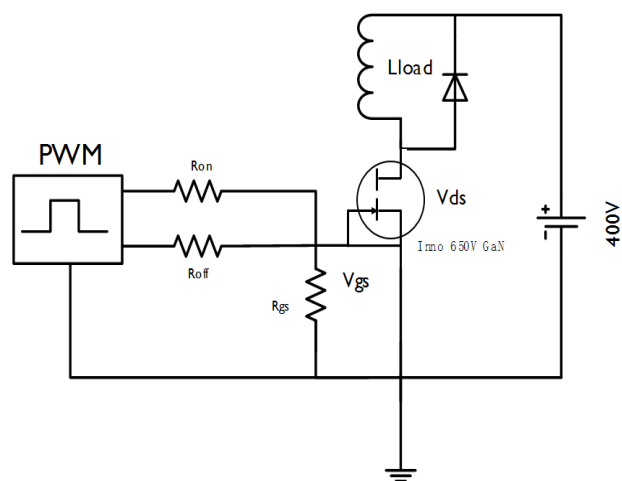
$Q_{oss} = f(V_{DS})$; Freq. = 100 kHz

Figure 21 Typ. Coss stored Energy



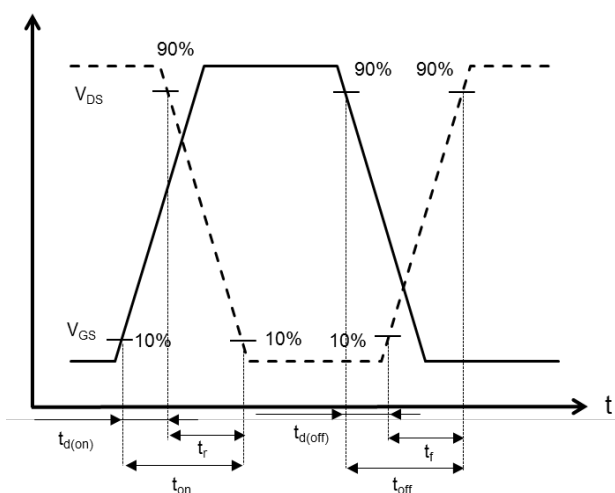
$E_{oss} = f(V_{DS})$; Freq. = 100 kHz

Figure 22 Typ. Switching times with inductive load

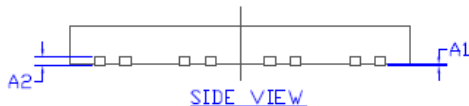
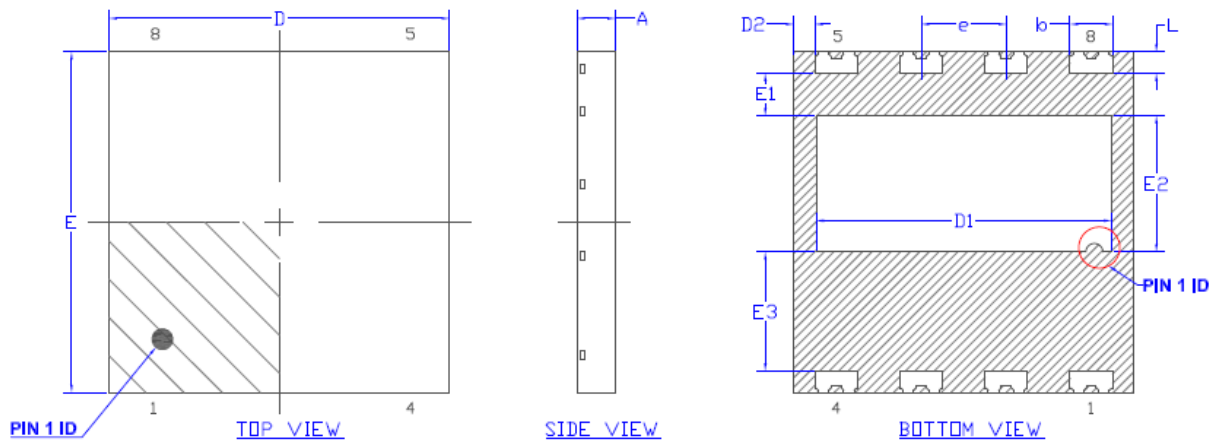


$V_{DS}=400V$, $I_D=5A$, $L_{load}=800\mu H$, $V_{GS}=6V$, $R_{on}=10\Omega$,
 $R_{off}=2\Omega$, $R_{gs}=10k\Omega$

Figure 23 Typ. Switching times waveform

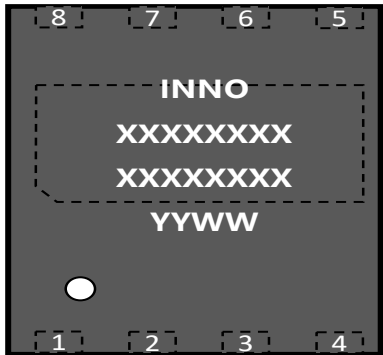


10.Package outlines



SYMBOL	DIMENSION			SYMBOL	DIMENSION		
	MIN	NOM	MAX		MIN	NOM	MAX
A	0.80	0.90	1.00	E	8.00 B.S.C		
A1	0.00	0.02	0.05	E1	0.90	1.00	1.10
A2	---	0.203 ref	---	E2	3.10	3.20	3.30
b	0.95	1.00	1.05	E3	2.70	2.80	2.90
D	8.00 B.S.C			e	2.00 B.S.C		
D1	6.84	6.94	7.04	L	0.40	0.50	0.60
D2	0.40	0.50	0.60				

Notes:
(1) Dimension and tolerance conform to ASME Y14.5-2009.
(2) All dimensions are in millimeters.
(3) Lead coplanarity shall be 0.1 millimeters max.
(4) Complies with JEDEC MO-229.
(5) Drawing is not to scale.



Row	Description	Example
Row 1	Company name	INNO
Row 2	Product code (In short)	XXXXXXXX
Row 3	ASSY lot No.	XXXXXXXX
Row 4	Date code	YYWW

11.Revision history

Major changes since the last revision

Revision	Date	Description of changes
1.0	2021-4-26	1.0 version release

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